

ULTRA-LOW PROFILE TERMINAL

TLH Mates with:

SLH

SLH Mates with:

TLH

SPECIFICATIONS

Insulator Material:

Black Liquid Crystal Polymer

Contact Material:

Copper Alloy

Plating:

Au over 50 μ" (1.27 μm) Ni

Current Rating:

2.1 A per pin

(2 pins powered)

Operating Temp Range:

-55 °C to +125 °C

RoHS Compliant:

Yes

PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max

RECOGNITIONS



FILE NO. E111594

TLH

NO. OF
POSITIONSLEAD
STYLEPLATING
OPTION

D

OPTION

OPTION

-010, -020,
-030, -040, -050
(Per Row)

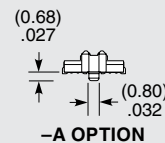
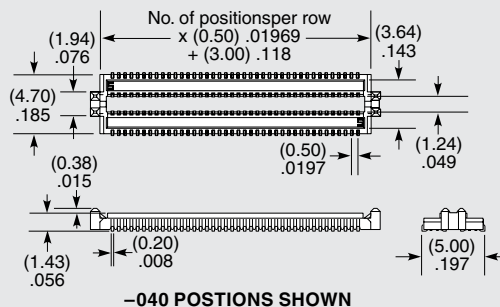
-0.50
= 0.50 mm

-G
= 10 μ" (0.25 μm)
Gold in contact,
Gold flash on tail

-A
= Alignment
Pin

-K
= (3.00 mm)
.118" DIA
Polyimide
Film
Pick &
Place Pad

-040 & -050 POSITIONS
PRELIMINARY



HIGH-SPEED CHANNEL PERFORMANCE

TLH/SLH @ 2 mm Mated Stack Height
Rating based on Samtec reference channel.

28
Gbps

SLH

NO. OF
POSITIONSLEAD
STYLEPLATING
OPTION

D

OPTION

OPTION

-010, -020,
-030, -040, -050
(Per Row)

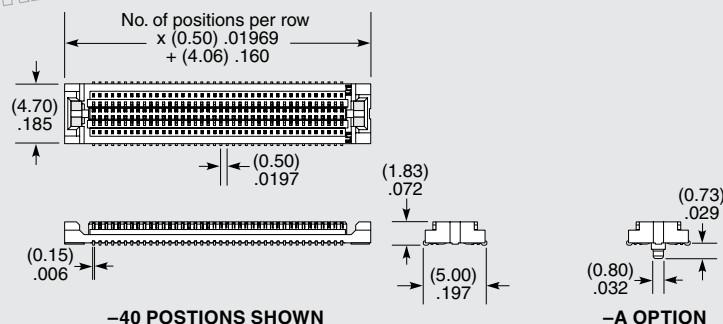
-1.50
= 1.50 mm

-G
= 10 μ" (0.25 μm)
Gold in contact,
Gold flash on tail

-A
= Alignment
Pin

-K
= (3.00 mm)
.118" DIA
Polyimide
Film
Pick &
Place Pad

-040 & -050 POSITIONS
PRELIMINARY



Note: Some lengths,
styles and options are
non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.TOBY.CO.UK

All parts within this catalog are built to Samtec's specifications.
Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.